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Docket No.: 4448-0173PUS1
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Chen-Jung TSAI et al.

Application No.: 10/726,577

Confirmation No.: 5109

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Art Unit: 2815

For: DUAL CHIPS STACKED PACKAGING
STRUCTURE

Examiner: J. A. Fenty

INFORMATION DISCLOSURE STATEMENT
(SUBMISSION AFTER NOTICE OF ALLOWANCE
BUT PRIOR TO PAYMENT OF THE ISSUE FEE)

MS: ISSUE FEE
Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

Sir:

Pursuant to 37 C.F.R. §§ 1.97 and 1.98, applicant(s) hereby submit(s) an Information Disclosure Statement for consideration by the Examiner.

I. **LIST OF PATENTS, PUBLICATIONS OR OTHER INFORMATION**

The patents, publications, or other information submitted for consideration by the Office are listed on the PTO-SB08(s), attached hereto.